Highlights of the 21st IMAPS Device Packaging Conference (DPC)

By Amy Lujan. General Chair Device Packaging 2025

The 21st IMAPS Device Packaging Conference (DPC 2025) set a new attendance record of more than 1,050 attendees. This beat the previous year's record by almost 40%. IMAPS leadership and conference attendees alike had many positive things to say about the new venue, which was a key part of enabling the growth of the conference.

The conference brought together industry pioneers and researchers who provided valuable insights into cutting-edge packaging solutions that drive AI acceleration, automotive electronics, high-performance computing, and much more.

This year brought a major focus on AI, covered by an evening panel and our Global Business Council (GBC) plenary session.

The popular GBC focused this year on "Scaling AI from Datacenter to Consumer," with industry thought leaders from Marvell, PDF Solutions, Qualcomm, TechSearch International and YOLE Group. The evening panel's lively discussion covered the topic of "Preparing for the Coming AI Winter?" and it concluded that there is no worry about Winter! The panel consisted of participants from ASE, Intel, STATS ChipPAC, IBM and Amkor.

Our keynote sessions were full to capacity with engaging presentations from IBM, Absolics, ScaleFlux, and Arizona State University/SHIELD. The program ran four concurrent technical tracks, up from three tracks in previous years. This year featured two full tracks on emerging technologies, including automotive, photonics, glass, additive manufacturing, and MEMS/sensors. Of particular interest to attendees were the photonics and glass-based substrates sessions, with standing room only. The other two tracks focused on the tried-and-true topics of 2D/3D heterogeneous integration, flip-chip, and wafer-level packaging, all of which continue to be integral to our industry.

The busy international exhibit hall drew in the entire industry supply chain and is always a critical complement to the conference's global technical program. This year we were able to accommodate more booths than ever, and there was still a waitlist for exhibitors.

Many exhibitors commented on the meaningful conversations they had with visitors and the ability to expand their connections. IMAPS leadership is already reviewing the 2026 meeting space allocations to potentially add booths to expand to an even larger exhibit hall in March 2026 when we return to The Sheraton at Wild Horse Pass.

Our evening interactive poster session was a hit with 25 posters presented in a beautiful outdoor setting overlooking the reservation and desert backdrop.

Attendees were very engaged with the poster presenters, asking the type of detailed questions that are more difficult to accommodate in oral sessions.

The posters were followed by the 3D InCites Back Yard Olympics—a fun team competition with six games and a lot of laughs. Congratulations to NAMICs, the gold winning team.

Each year, attendees provide feedback that this event is unique with its multitude of networking opportunities and the opportunity to directly converse with industry leaders, researchers, new talent and suppliers.

We were thrilled with the significant student participation this year from Arizona State University and the University of Arizona. One-hundred plus students participated in our professional development courses and had the ability to speak directly with our subject matter industry experts. ASU, University of Arizona, and the Chandler Unified School District participated with tabletop exhibits.

This summer, Chandler Arizona's Hamilton High School (in partnership with University of Arizona) is kicking off the nation's first Career and Technical Education Program in Semiconductor Manufacturing. We are excited about this level of student activity and the chance to help develop the industry's future workforce.

We look forward to DPC 2026 at the same venue on March 2-5, 2026.